



PICs for Optical Interconnects

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Deadline for manuscript
submissions:

closed (10 October 2019)

Message from the Guest Editors

The main purpose of this Special Issue is to cover all topics of latest research and developments in the field of “PICs for Optical Interconnects”. This will be an open call for papers and we are seeking research contributions in the following areas:

1. Optical interconnect system architectures
2. Active optical cables and mid-board optics
3. On-chip and short-reach optical interconnect technologies
4. Electrical–optical PCB technologies and pluggable optical connectors
5. 3D integration, assembly and packaging
6. Large scale photonic switches and routing technologies
7. Silicon photonic PICs and III-V/Si laser sources
8. Optical memories and optically-interconnected memories
9. Photonic crystals, plasmonic devices and novel materials
10. Neuromorphic photonics

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Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal Applied Sciences has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

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